

SSC8041GN6

P-Channel Enhancement Mode MOSFET

> Features

V _{DS}	V_{GS}	R _{DS(ON)}	l _D
-40V	+20V	9mΩ@-10V	-58A
-40 V	<u> </u>	16mΩ@-4V5	-507

> Description

This SSC8041GN6 uses advanced trench technology to provide excellent RDSON and low gate charge. The complementary MOSFETS may be used to form a level shifted high side switch, and for a host of other applications.

100% UIS + ΔVDS + Rg Tested!

Applications

- Load Switch
- PWM Application
- Power Management

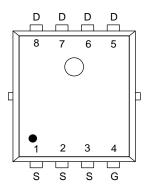
> Ordering Information

Device	Package	Shipping
SSC8041GN6	PDFN5X6-8L	5000/Reel

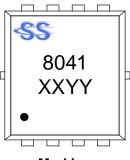
> Pin configuration



PDFN5X6-8L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)



➤ Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain-to-Source Volta	ige	-40	V
V _{GSS}	Gate-to-Source Volta	ge	±20	V
	Cartinosas Dania Comunant d	T _C =25℃	-58	Δ.
ID	Continuous Drain Current d	T _C =100°C	-32	- A
	Continuous Dusin Comment 3	T _A =25℃	-18	Δ.
IDSM	Continuous Drain Current ^a	T _A =70°C	-13	- A
Ірм	Pulsed Drain Curren	t ^b	-230	Α
Б	Davida Disabilitation C	Tc=25℃	43	10/
P _D	Power Dissipation ^c	T _C =100°C	17	W
-	De la Bississita d	T _A =25℃	4.2	107
P _{DSM}	Power Dissipation ^a	T _A =70°C	2.7	W
I _{AS}	Avalanche Current b L=0.5mH	Avalanche Current b L=0.5mH Single Pulse		Α
Eas	Avalanche Energy ^b L=0.5mH	Single Pulse	75	mJ
TJ	Operation junction temper	erature	-55~150	°C
T _{STG}	Storage temperature ra	ange	-55~150	℃

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance a	30	°C AA/
$R_{ heta JC}$	Junction-to-Case Thermal Resistance	2.9	°C/W

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

SSC-V1.0 www.afsemi.com Analog Future



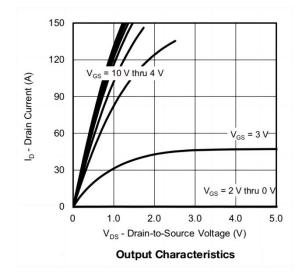


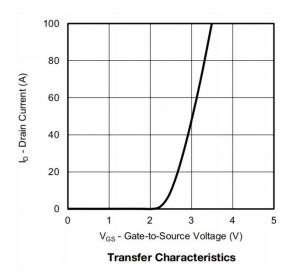
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

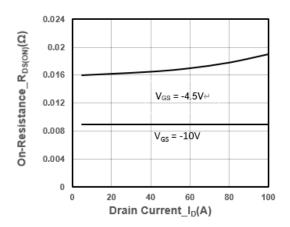
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_{D} = -250\mu A$	-40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250uA$	-1.2	-2.1	-3	٧
Drain Course On Registeres	Б	V _{GS} = -10V, I _D = -20A		9	13	0
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -4.5V, I _D = -10A		16	23	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -40V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	V _{DS} = -5V, I _D = -12A		40		s
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = -5A			1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		4		Ω
Input Capacitance	Ciss	V 20V V 0V		2600		
Output Capacitance	Coss	V _{DS} = -20V, V _{GS} = 0V,		260		pF
Reverse Transfer Capacitance	Crss	f = 1MHz		230		
Total Gate Charge	Q _G	10)/)/ 00)/		16		
Gate to Source Charge	Q _{GS}	V _{GS} = -10V, V _{DS} = -20V,		5		nC
Gate to Drain Charge	Q _{GD}	I _D = -15A		6		
Turn-on Delay Time	T _{D(ON)}			13		
Rise Time	Tr	V _{GS} = -10V, V _{DS} = -10V,		13		
Turn-off Delay Time	T _{D(OFF)}	$R_L = 10\Omega$, $R_G = 1\Omega$,		25		ns
Fall Time	T _f			9		
Diode Recovery Time	Trr	I _F =-20A, di/dt=500A/us		19		ns
Diode Recovery Charge	Q _{rr}	I _F =-20A, di/dt=500A/us		22		nC



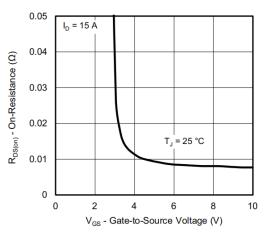
> Typical Performance Characteristics (T_A=25℃ unless otherwise noted)



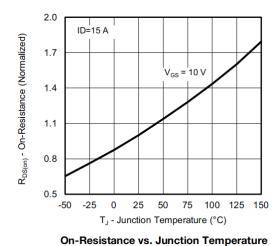


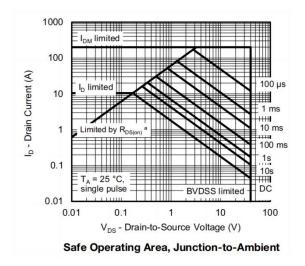


On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

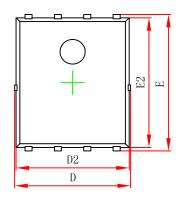


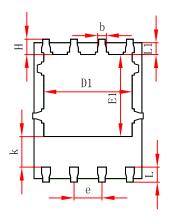


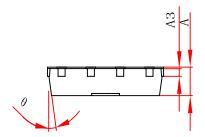
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> Package Information





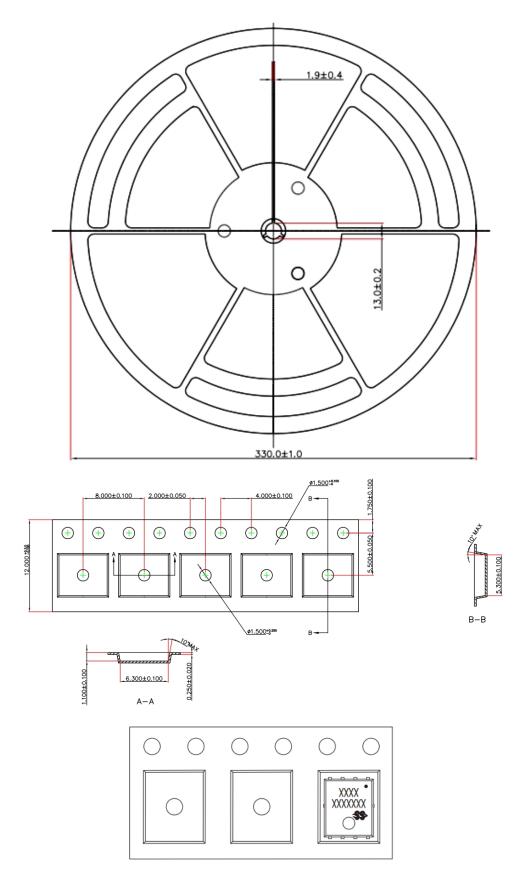


Package: PDNF5X6-8L

Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	REF.	0.010	REF.	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270TYP.		0.050	TYP.	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	



> Tape and Reel





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